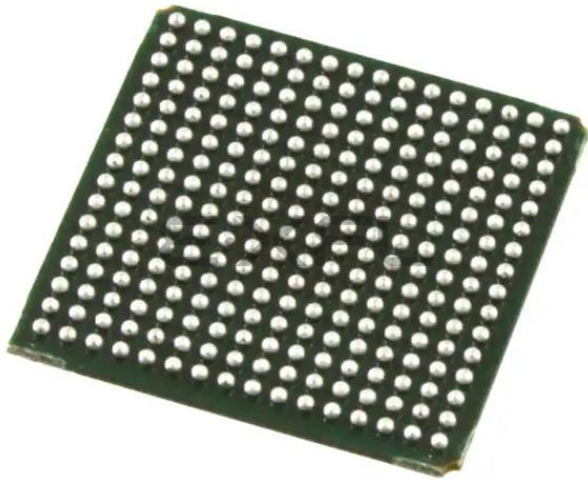




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	2704
Total RAM Bits	113664
Number of I/O	160
Number of Gates	210000
Voltage - Supply	2.3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfx200eb-03f256c

Architecture Overview

The ispXPGA architecture is a symmetrical architecture consisting of an array of Programmable Function Units (PFUs) enclosed by Input Output Groups (PICs) with columns of sysMEM Embedded Block RAMs (EBRs) distributed throughout the array. Figure 1 illustrates the ispXPGA architecture. Each PIC has two corresponding sysIO blocks, each of which includes one input and output buffer. On two sides of the device, between the PICs and the sysIO blocks, there are sysHSI High-Speed Interface blocks. The symmetrical architecture allows designers to easily implement their designs, since any logic function can be placed in any section of the device.

The PFUs contain the basic building blocks to create logic, memory, arithmetic, and register functions. They are optimized for speed and flexibility allowing complex designs to be implemented quickly and efficiently.

The PICs interface the PFUs and EBRs to the external pins of the device. They allow the signals to be registered quickly to minimize setup times for high-speed designs. They also allow connections directly to the different logic elements for fast access to combinatorial functions.

The sysMEM EBRs are large, fast memory elements that can be configured as RAM, ROM, FIFO, and other storage types. They are designed to facilitate both single and dual-port memory for high-speed applications.

These three components of the architecture are interconnected via a high-speed, flexible routing array. The routing array consists of Variable Length Interconnect (VLI) lines between the PICs, PFUs, and EBRs. There is additional routing available to the PFU for feedback and direct routing of signals to adjacent PFUs or PICs.

The sysIO blocks consist of configurable input and output buffers connected directly to the PICs. These buffers can be configured to interface with 16 different I/O standards. This allows the ispXPGA to interface with other devices without the need for external transceivers.

The sysHSI blocks provide the necessary components to allow the ispXPGA device to transfer data at up to 800Mbps using the LVDS standard. These components include serializing, de-serializing, and clock data recovery (CDR) logic.

The sysCLOCK blocks provide clock multiplication/division, clock distribution, delay compensation, and increased performance through the use of PLL circuitry that manipulates the global clocks. There is one sysCLOCK block for each global clock tree in the device.

Set/Reset signal controls all the registers for each PFU. This common Set/Reset signal is composed of the logical OR term of the Global Set/Reset signal (GSR) and the selected signal from routing. The polarity of this signal is not controllable inside the PFU. The polarity of the Global Set/Reset signal (GSR) is programmable. Figure 9 shows the Clock Enable and Output Enable selection for each PFU.

Figure 7. Clock Selection per PFU

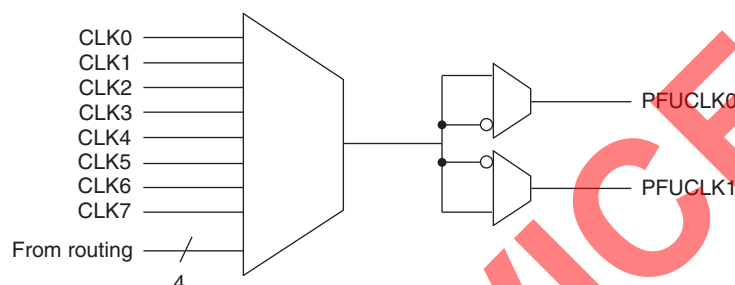


Figure 8. Set/Reset Selection per PFU

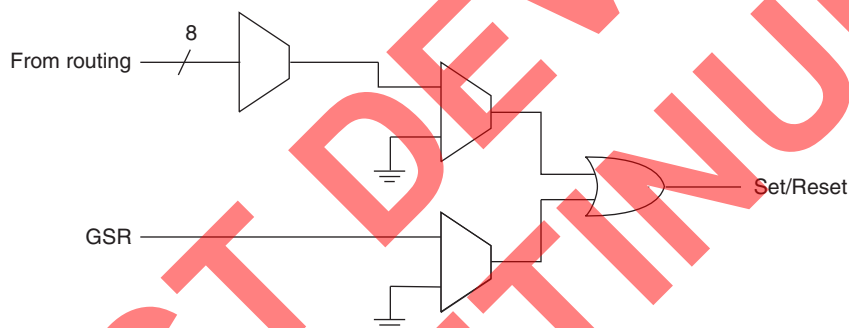
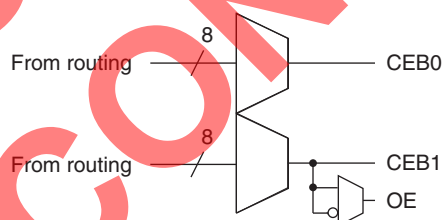


Figure 9. Clock Enable and Output Enable Selection per PFU

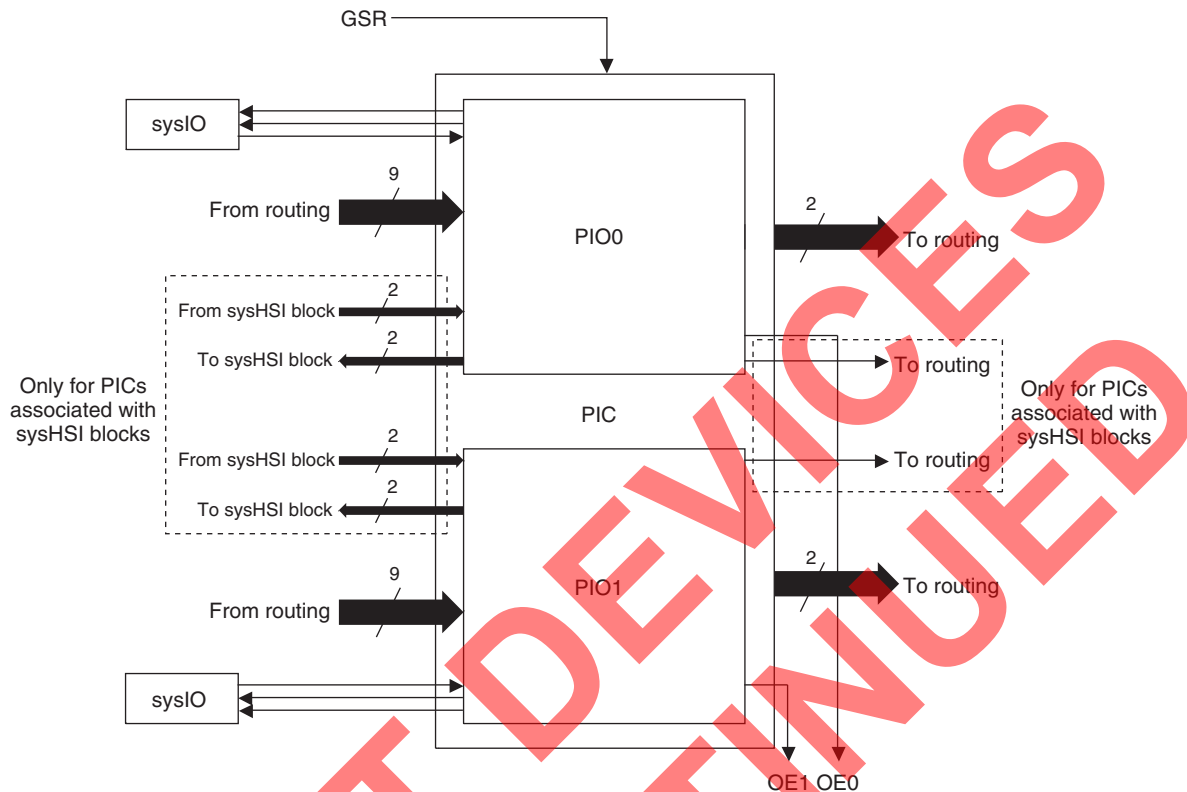


Programmable Input/Output Cell

The Programmable Input/Output Cell (PIC) is an essential part of the symmetrical architecture of the ispXPGA Family. The PICs interface the PFUs and EBRs to the sysIO and sysHSI blocks of the device.

Each PIC contains two Programmable Input/Outputs (PIOs) with a total of 21 inputs and 10 outputs. There are 18 inputs from routing, two inputs from the sysIO buffers, and the Global Set/Reset signal. Four outputs of the PIC connect to routing and two outputs are available as Output Enables for the tri-statable Long Lines. The remaining four outputs feed the sysIO buffers directly (one output enable and one output to each). Each PIC associated with a sysHSI block has four additional inputs and six additional outputs to support the sysHSI blocks. The four additional inputs come from the sysHSI block associated with the PIC. The four of the six additional outputs come from the PIC outputs and feed the sysHSI block, while the remaining two outputs feed routing. Figure 10 shows the block diagram of the PIC with the sysHSI block inputs and outputs.

Figure 10. ispXPGA PIC

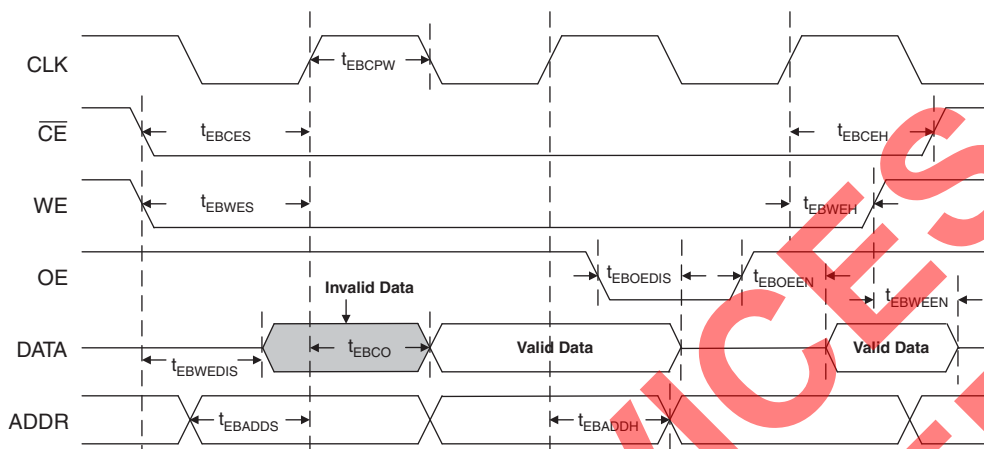


Programmable Input/Output

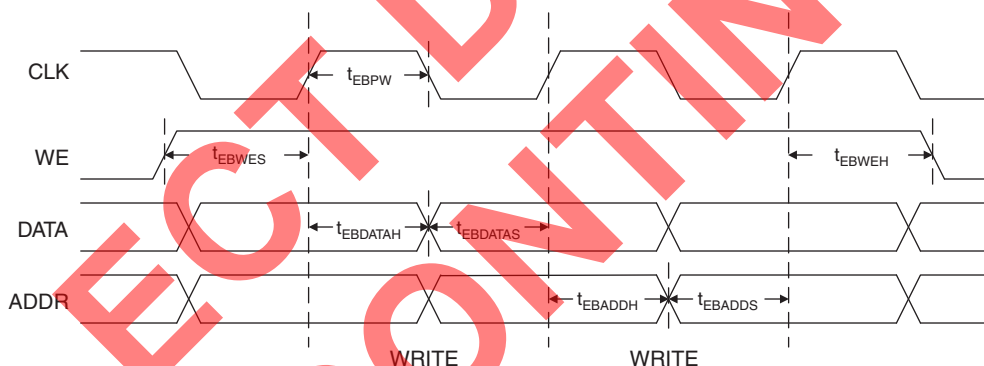
The PIO is the building block of a PIC. The PIO has a total of 11 inputs and five outputs. Nine of the 11 inputs are generated from routing. The inputs from routing are the PIO Input (IN), Feed-Thru (FT), Clock (CLK), Input Clock Enable (ICE), Input Set/Reset (ISR), Output Clock Enable (OCEN), Output Set/Reset (OSR), PIO Output Enable (OEN), and PIO Input Enable (IEN). The remaining inputs are the sysIO input buffer signal and the Global Set/Reset signal. Three of the five outputs (OUT0, OUT1, and OE) feed routing. The last two outputs feed the sysIO buffer directly as the output and output enable of the sysIO output buffer.

PIOs associated with sysHSL blocks contain two additional inputs and outputs to support the sysHSL block. The two inputs come from the sysHSL block associated with the PIO, and the two outputs feed the sysHSL block. One of the inputs routes directly through the PIO to routing, while the other is multiplexed with the Feed-Thru, register bypass, and Q output of the register to form the OUT1 output of the PIO. The outputs to the sysHSL block are the same signals as the outputs which feed the sysIO buffers (sysIO Output and sysIO Output Enable).

Each PIO has an input register, an output register, and an output enable register as shown in Figure 11. The input register path of the PIO has a 'delay' option, which slows the data-flow. A two-input OR function of the Global Set/Reset (GSR) and Set/Reset (ISR or OSR) signals creates the set/reset term for the respective registers. Each PIO has two pairs of set/reset and clock enable signals. One is exclusive to the input register, whereas the other is common for both the output and output enable registers. The clock (CLK) is common to all registers in a PIO, and the polarity of the clock is controllable. The input, output, and the output enable registers can be configured as a latch or D-type flip-flop. Each PIO is capable of generating an output enable signal, which in turn becomes a PIC output.

Figure 13. EBR Synchronous Read Timing Diagram

Synchronous Write: The WE signal controls the synchronous write operation. When the WE signal is high, the write operation begins. Once the address and data are present and the Output Enable (OE) is active, a rising clock edge (or falling edge depending on polarity) causes the data to be stored into the EBR. Figure 14 illustrates the synchronous write timing.

Figure 14. EBR Synchronous Write Timing Diagram

Asynchronous Read: The WE signal controls the asynchronous read operation. When the WE signal is low, the read operation begins. Shortly after the address is present, the stored data is available on the DATA port. Figure 15 illustrates the asynchronous read timing. For more information about the EBR, refer to TN1028 [ispXPGA Memory Usage Guidelines](#).

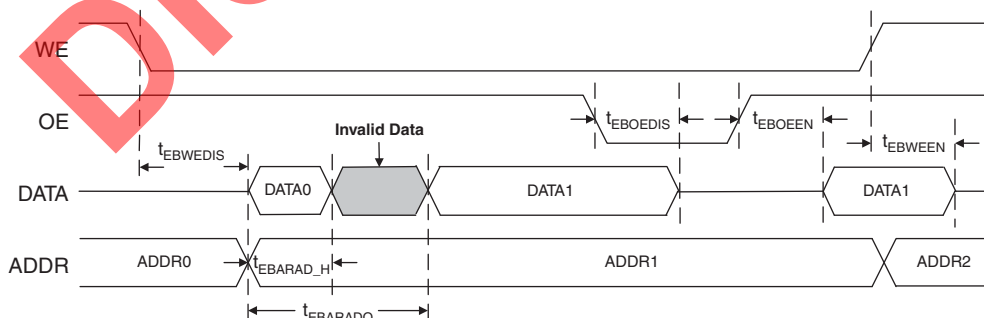
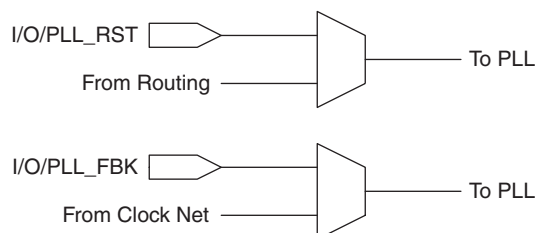
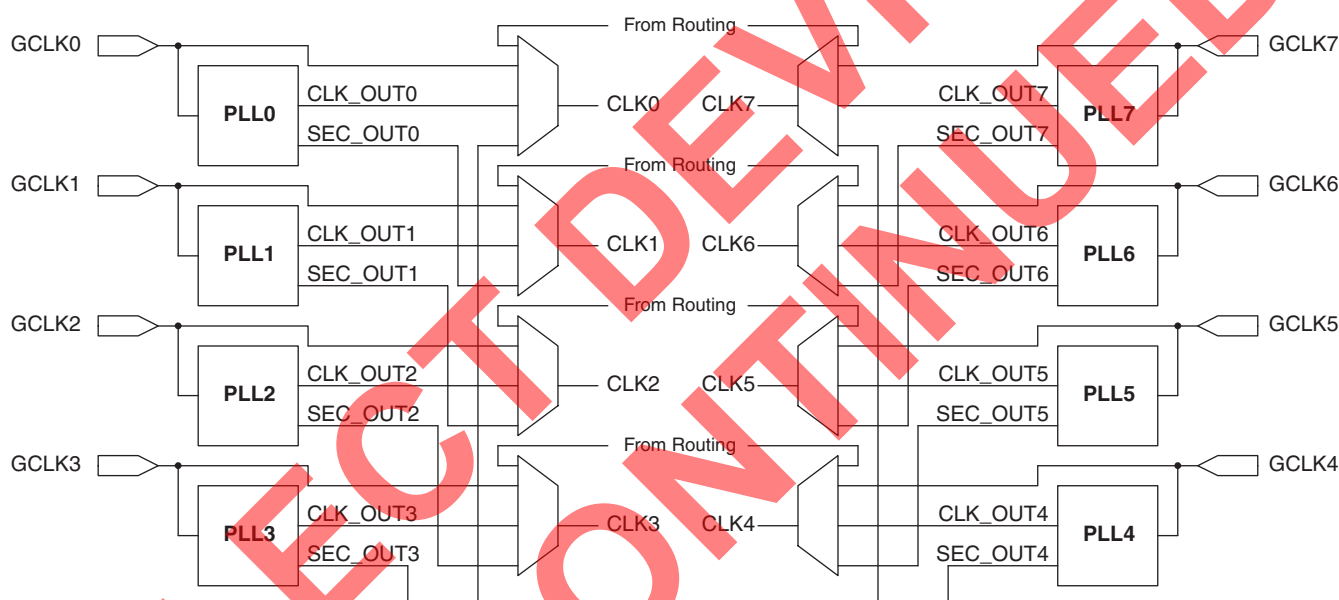
Figure 15. EBR Asynchronous Read Timing Diagram

Figure 17. ispXPGA PLL_RST and PLL_FBK Generation

Clock Routing

The Global Clock Lines (GCLK) have two sources, their dedicated pins and the sysCLOCK circuit. Figure 18 illustrates the generation of the Global Clock Lines.

Figure 18. Global Clock Line Generation

sysIO Capability

All the ispXPGA devices have eight sysIO banks, where each bank is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCO}) and reference voltage (V_{REF}) resources allowing each bank complete independence from the others. Each I/O is individually configurable based on the bank's V_{CCO} and V_{REF} settings. In addition, each I/O has configurable drive strength, weak pull-up, weak pull-down, or a bus-keeper latch. Table 4 lists the number of I/Os supported per bank in each of the ispXPGA devices. In addition, 5V tolerant inputs are specified within an I/O bank that is connected to V_{CCO} of 3.0V to 3.6V for LVCMOS 3.3, LVTTL and PCI interfaces.

Table 5 lists the sysIO standards with the typical values for V_{CCO} , V_{REF} and V_{TT} .

The TOE, JTAG TAP pins, PROGRAM, CFG0 and DONE pins of the ispXPGA device are the only pins that do not have the sysIO capabilities. The TOE and CFG0 pins operate off the V_{CC} of the device, supporting only the LVCMOS standard corresponding to the device supply voltage. The TAP pins have a separate supply voltage (V_{CCJ}), which determines the LVCMOS standard corresponding to that supply voltage.

There are three classes of I/O interface standards that are implemented in the ispXPGA devices. The first is the un-terminated, single-ended interface. It includes the 3.3V LVTTL standard along with the 1.8V, 2.5V, and 3.3V LVCMOS interface standards. Additionally, PCI and AGP-1X are subsets of this type of interface.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{IL}, I_{IH}^1	Input or I/O Low Leakage	$0 \leq V_{IN} < (V_{CCO} - 0.2V)$	—	—	10	μA
		$(V_{CCO} - 0.2V) \leq V_{IN} \leq 3.6V$	—	—	300	μA
I_{IH}^2	Input High Leakage Current	$3.6V < V_{IN} \leq 5.5V$ and $3.0V \leq V_{CCO} \leq 3.6V$	—	—	3	mA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH} (MAX)$	—	—	-150	μA
V_{BHT}	Bus Hold Trip Points		$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
C_1	I/O Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	
C_2	Clock Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	
C_3	Global Input Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. 5V tolerant inputs and I/Os should be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.
3. $T_A = 25^\circ C$, $f = 1.0MHz$.

sysIO Recommended Operating Conditions

Standard	V_{CCO} (V) ¹			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVC MOS 3.3	3.0	3.3	3.6	-	-	-
LVC MOS 2.5	2.3	2.5	2.7	-	-	-
LVC MOS 1.8 ²	1.65	1.8	1.95	-	-	-
LV TTL	3.0	3.3	3.6	-	-	-
PCI 3.3	3.0	3.3	3.6	-	-	-
AGP-1X	3.15	3.3	3.45	-	-	-
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	-	0.9	-
GTL+	-	-	-	0.882	1.0	1.122
LVDS	2.3	2.5	2.7	-	-	-
LVPECL	3.0	3.3	3.6	-	-	-
BLVDS	2.3	2.5	2.7	-	-	-

1. Inputs independent of V_{CCO} .

2. Design tool default setting.

ispXPGA 500B/C & ispXPGA 500EB/EC PFU Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5 ¹		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Reset/Set								
t _{LASSRO}	Asynchronous Set/Reset to Output	—	1.09	—	1.17	—	1.35	ns
t _{LASSRPW}	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t _{LASSRR}	Asynchronous Set/Reset Recovery	—	0.51	—	0.55	—	0.63	ns
t _{LSSR_S}	Synchronous Set/Reset Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t _{LSSR_H}	Synchronous Set/Reset Hold Time	0.03	—	0.03	—	0.03	—	ns

1. Only available for ispXPGA 500B and ispXPGA 500EB (2.5V/3.3V) devices.

Timing v.0.3

2. t_{LCTHRUL} quoted bit by bit.**ispXPGA 500B/C & ispXPGA 500EB/EC PIC Timing Parameters**

Parameter	Description	-5 ¹		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Register/Latch Delays								
t _{IO_CO}	Register Clock to Output Delay	—	1.00	—	1.07	—	1.23	ns
t _{IO_S}	Register Setup Time (Data before Clock)	0.05	—	0.05	—	0.06	—	ns
t _{IO_H}	Register Hold Time (Data after Clock)	0.06	—	0.06	—	0.07	—	ns
t _{IOCE_S}	Register Clock Enable Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t _{IOCE_H}	Register Clock Enable Hold Time	0.13	—	0.13	—	0.15	—	ns
t _{IO_GO}	Latch Gate to Output Delay	—	0.78	—	0.84	—	0.97	ns
t _{IOL_S}	Latch Setup Time	0.05	—	0.05	—	0.06	—	ns
t _{IOL_H}	Latch Hold Time	0.06	—	0.06	—	0.07	—	ns
t _{IOLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns
t _{IOASRO}	Asynchronous Set/Reset to Output	—	1.11	—	1.19	—	1.37	ns
t _{IOASRPW}	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t _{IOASRR}	Asynchronous Set/Reset Recovery Time	—	0.23	—	0.25	—	0.29	ns
Input/Output Delays								
t _{IOBUF}	Output Buffer Delay	—	0.98	—	1.05	—	1.21	ns
t _{IOIN}	Input Buffer Delay	—	0.65	—	0.70	—	0.81	ns
t _{IOEN}	Output Enable Delay	—	0.52	—	0.56	—	0.64	ns
t _{IODIS}	Output Disable Delay	—	-0.12	—	-0.11	—	-0.09	ns
t _{IIFT}	Feed-thru Delay	—	0.19	—	0.20	—	0.23	ns

1. Only available for ispXPGA 500B and ispXPGA 500EB (2.5V/3.3V) devices.

Timing v.0.3

ispXPGA 1200B/C & ispXPGA 1200EB/EC PFU Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5 ¹		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Reset/Set								
t _{LASSRO}	Asynchronous Set/Reset to Output	—	1.09	—	1.17	—	1.35	ns
t _{LASSRPW}	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t _{LASSRR}	Asynchronous Set/Reset Recovery	—	0.51	—	0.55	—	0.63	ns
t _{LSSR_S}	Synchronous Set/Reset Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t _{LSSR_H}	Synchronous Set/Reset Hold Time	0.03	—	0.03	—	0.03	—	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

Timing v.2.1

2. t_{LCTHRUL} quoted bit by bit.**ispXPGA 1200B/C & ispXPGA 1200EB/EC PIC Timing Parameters**

Parameter	Description	-5 ¹		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Register/Latch Delays								
t _{IO_CO}	Register Clock to Output Delay	—	1.01	—	1.09	—	1.25	ns
t _{IO_S}	Register Setup Time (Data before Clock)	0.05	—	0.05	—	0.06	—	ns
t _{IO_H}	Register Hold Time (Data after Clock)	0.06	—	0.06	—	0.07	—	ns
t _{IOCE_S}	Register Clock Enable Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t _{IOCE_H}	Register Clock Enable Hold Time	0.13	—	0.13	—	0.15	—	ns
t _{IO_GO}	Latch Gate to Output Delay	—	0.85	—	0.91	—	1.05	ns
t _{IOL_S}	Latch Setup Time	0.05	—	0.05	—	0.06	—	ns
t _{IOL_H}	Latch Hold Time	0.06	—	0.06	—	0.07	—	ns
t _{IOLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns
t _{IOASRO}	Asynchronous Set/Reset to Output	—	1.17	—	1.26	—	1.45	ns
t _{IOASRPW}	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t _{IOASRR}	Asynchronous Set/Reset Recovery Time	—	0.23	—	0.25	—	0.29	ns
Input/Output Delays								
t _{IOBUF}	Output Buffer Delay	—	0.99	—	1.06	—	1.22	ns
t _{IOIN}	Input Buffer Delay	—	0.71	—	0.76	—	0.87	ns
t _{IOEN}	Output Enable Delay	—	0.52	—	0.56	—	0.64	ns
t _{IODIS}	Output Disable Delay	—	-0.11	—	-0.10	—	-0.09	ns
t _{IOFT}	Feed-thru Delay	—	0.19	—	0.20	—	0.23	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

Timing v.2.1

sysHSI Block AC Specifications

Operating Frequency Ranges

Symbol	Description	Mode	Test Condition	Device	-5 ¹		-4		-3		Units
					Min.	Max.	Min.	Max.	Min.	Max.	
f _{CLK}	Reference Clock Frequency	SS:CAL		LFX125B/C	50	200	50	200	50	200	MHz
				LFX200B/C	50	188	50	188	50	188	
				LFX500B/C	50	188	50	188	50	188	
				LFX1200B/C	50	175	50	175	50	175	
		10B12B		LFX125B/C	33	67	33	67	33	67	MHz
				LFX200B/C	33	63	33	63	33	63	
				LFX500B/C	33	63	33	63	33	63	
				LFX1200B/C	33	58	33	58	33	58	
		8B10B		LFX125B/C	40	80	40	80	40	80	MHz
				LFX200B/C	40	75	40	75	40	75	
				LFX500B/C	40	75	40	75	40	75	
				LFX1200B/C	40	70	40	70	40	70	
f _{SIN} ²	Serial Input	SS:CAL	with eoSIN	LFX125B/C	400	800	400	800	400	800	Mbps
				LFX200B/C	400	750	400	750	400	750	
				LFX500B/C	400	750	400	750	400	750	
				LFX1200B/C	400	700	400	700	400	700	
		10B12B	with eoSIN	LFX125B/C	400	800	400	800	400	800	Mbps
				LFX200B/C	400	750	400	750	400	750	
				LFX500B/C	400	750	400	750	400	750	
				LFX1200B/C	400	700	400	700	400	700	
		8B10B	with eoSIN	LFX125B/C	400	800	400	800	400	800	Mbps
				LFX200B/C	400	750	400	750	400	750	
				LFX500B/C	400	750	400	750	400	750	
				LFX1200B/C	400	700	400	700	400	700	
f _{OUT} ²	Serial Out	LVDS	CL = 5 pF, RL = 100 Ω f _{CLK} with no jitter	LFX125B/C	400	800	400	800	400	800	Mbps
				LFX200B/C	400	750	400	750	400	750	
				LFX500B/C	400	750	400	750	400	750	
				LFX1200B/C	400	700	400	700	400	700	

1. Only available for ispXPGA 125B, 200B, 500B and 1200B (2.5V/3.3V) devices.

2. f_{SIN} and f_{OUT} speeds are supported at V_{CC} and V_{CCP} at 1.7V to 1.9V for ispXPGA 1.8V devices.

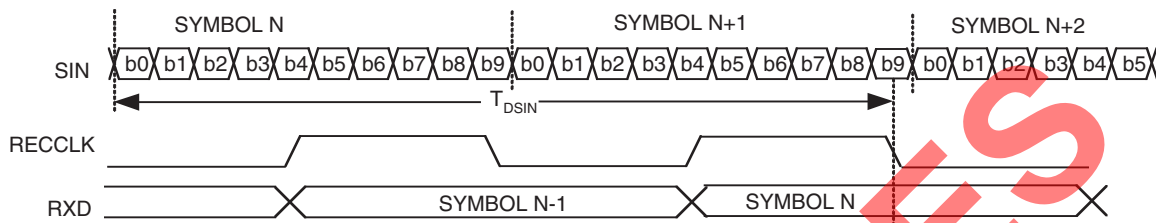
LOCKIN Time

Symbol	Description	Mode	Condition	Min	Max	Unit
t _{SCLOCK}	CSPLL Lock Time	All	After input is stabilized		25	μ S
t _{CDRLOCK}	CDRPLL Lock-in Time	SS	With SS mode sync pattern		1024	t _{RCP} ¹
		10B12B	With 10B12B sync pattern		1024	t _{RCP}
		8B10B	With 8B10B idle pattern		960	t _{RCP}
t _{SYNC}	SyncPat Length	SS		1200		t _{RCP}
t _{CAL}	CAL Duration	SS		1100		t _{RCP}
t _{SUSYNC}	SyncPat Set-up Time to CAL	SS		50		t _{RCP}
t _{HDSYNC}	SyncPat Hold Time from CAL	SS		50		t _{RCP}

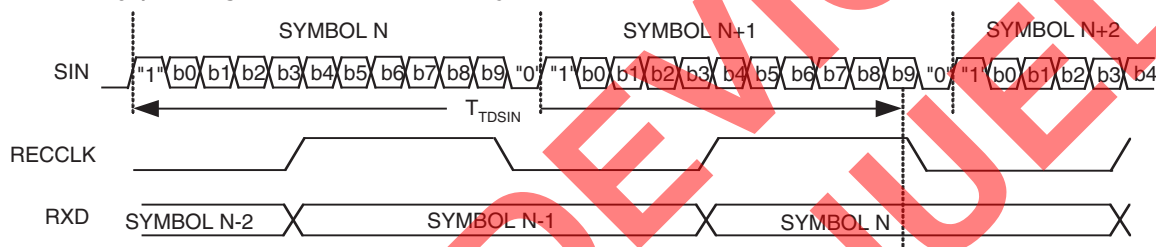
1. REFCLK clock period.

Deserializer Timing

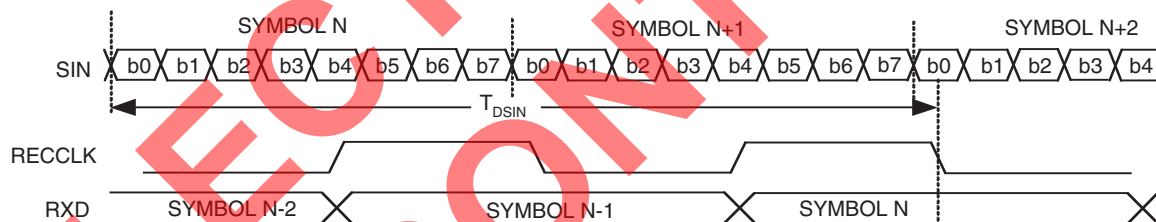
8B/10B DESERIALIZER DELAY TIMING



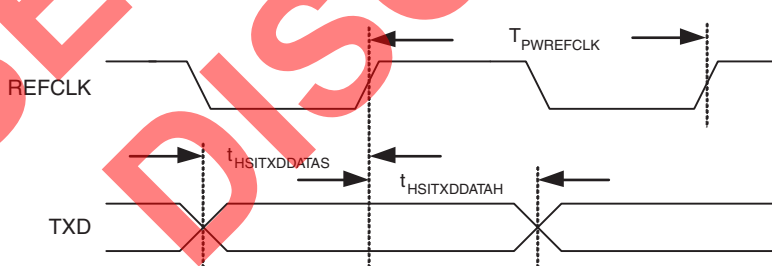
10B/12B DESERIALIZER DELAY TIMING



CDRX_SS DESERIALIZER DELAY TIMING



INTERNAL TIMING FOR sysHSI BLOCK



ispXP sysCONFIG Port Timing Specifications

Symbol	Timing Parameter	Min.	Typ.	Max.	Units
sysCONFIG Write Cycle Timing					
t_{SUCS}	Input setup time of CS to CCLK rise	10	—	—	ns
t_{HCS}	Hold time of CS to CCLK Rise	0	—	—	ns
t_{SUWD}	Input setup time of write data to CCLK rise	12	—	—	ns
t_{HWD}	Hold time of write data to CCLK rise	0	—	—	ns
t_{PRGM}	Low time to reset device SRAM	5	—	50	ns
t_{WINIT}	INIT pulse width	—	—	5	ms
t_{IODISS}	User I/O disable	—	—	30	ns
t_{IOENSS}	User I/O enable	—	—	30	ns
t_{WH}	Write clock High pulse width	12	—	—	ns
t_{WL}	Write clock Low pulse width	12	—	—	ns
f_{MAXW}	Write f_{MAX}	—	—	33	MHz
sysCONFIG Read Cycle Timing					
t_{HREAD}	Hold time of READ to CCLK rise	0	—	—	ns
t_{SUREAD}	Input setup time of READ High to CCLK rise	30	—	—	ns
t_{RH}	READ clock high pulse width	12	—	—	ns
t_{RL}	READ clock low pulse width	15	—	—	ns
f_{MAXR}	Read f_{MAX}	—	—	33	MHz
t_{CORD}	Clock to out for read data	—	—	25	ns

Boundary Scan Timing

Parameter	Description	Min.	Max.	Units
t_{BTCP}	TCK [BSCAN] Clock Pulse Width	40	—	ns
t_{BTCPH}	TCK [BSCAN] Clock Pulse Width High	20	—	ns
t_{BTCPL}	TCK [BSCAN] Clock Pulse Width Low	20	—	ns
t_{BTS}	TCK [BSCAN] Setup Time	8	—	ns
t_{BTH}	TCK [BSCAN] Hold Time	10	—	ns
t_{BTRF}	TCK [BSCAN] Rise/Fall Time	50	—	mV/ns
t_{BTCO}	TAP Controller Falling Edge of Clock to Valid Output	—	18	ns
$t_{BTCODIS}$	TAP Controller Falling Edge of Clock to Valid Disable	—	18	ns
t_{BTCOEN}	TAP Controller Falling Edge of Clock to Valid Enable	—	18	ns
t_{BTCRS}	BSCAN Test Capture Register Setup Time	8	—	ns
t_{BTCRH}	BSCAN Test Capture Register Hold Time	25	—	ns
t_{BUTCO}	BSCAN Test Update Register, Falling Edge of Clock to Valid Output	—	45	ns
$t_{BTUODIS}$	BSCAN Test Update Register, Falling Edge of Clock to Valid Disable	—	20	ns
$t_{BTUPOEN}$	BSCAN Test Update Register, Falling Edge of Clock to Valid Enable	—	20	ns

Signal Descriptions¹

Signal Name	Signal Type	Description
General Purpose		
BKy_IOx ^{1,2}	Input/Output	General purpose I/O number x in I/O Bank y
GCLKn/In ⁷	Input	Global clock/input ⁸
GSR	Input	Global Set/Reset
NC	—	No Connect
GND	GND	Ground
V _{CC}	VCC	Core logic power supply
V _{CCJ}	VCC	IEEE 1149.1 TAP power supply
V _{CCOy} ²	VCC	I/O Bank y power supply
V _{REFy} ²	Input	I/O Bank y reference voltage
D _{XN} , D _{XP}	Output	Temperature Sensing Diodes, provide a differential voltage, which corresponds to the temperature of the device.
Test and Program/Configuration		
TMS	Input	Test Mode Select
TCK	Input	Test Clock
TDI	Input	Test Data In
TDO	Output	Test Data Out
TOE	Input	Test Output Enable tri-states all I/O pins when driven low
CFG0	Input	Selects the SRAM memory configuration type (Peripheral or E ² CMOS Refresh)
PROGRAMb	Input	Initiates download from E ² CMOS or the peripheral port to SRAM memory (active low)
DONE	Bi-directional	Indicates when configuration is complete
INITb	Bi-directional	Indicates the device is ready for programming (active low)
READ	Input	Selects the READ operation when in sysCONFIG mode
CCLK	Input	sysCONFIG Configuration Clock
CSb	Input	sysCONFIG Chip Select (active low)
DATA[0:7]	Bi-directional	sysCONFIG Peripheral Port Data I/O
sysCLOCK PLL³		
PLL_FBKz	Input	Optional external feedback
PLL_RSTz	Input	Optional external M divider reset
CLK_OUTz	Internal Signal	Clock output (routable to any I/O)
PLL_LOCKz	Internal Signal	Lock output (routable to any I/O)
GND _{P0}	GND	Left side PLL Ground
GND _{P1}	GND	Right side PLL Ground
V _{CCP0}	VCC	Left side PLL power supply
V _{CCP1}	VCC	Right side PLL power supply
sysHSI Block^{4,5}		
HSImA_SINP, HSImB_SINP	Input	P-side of differential serial data input
HSImA_SINN, HSImB_SINN	Input	N-side of differential serial data input
HSImA_SOUTP, HSImB_SOUTP	Output	P-side of differential serial data output
HSImA_SOUTN, HSImB_SOUTN	Output	N-side of differential serial data output
HSImA_SYDT, HSImB_SYDT	Internal Signal	Symbol alignment detect
HSImA_RECCLK, HSImB_RECCLK	Internal Signal	Recovered clock

ispXPGA Logic Signal Connections: 256-Ball fpBGA

256-fpBGA Ball	LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ²	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ²
C2	BK0_IO2	HSI0A_SOUTP	1P/HSI0	BK0_IO0	HSI0A_SOUTP	0P
-	GND (Bank 0)	-	-	-	-	-
D2	BK0_IO3	HSI0A_SOUTN	1N/HSI0	BK0_IO1	HSI0A_SOUTN	0N
B1	BK0_IO6	HSI0A_SINP	3P/HSI0	BK0_IO4	HSI0A_SINP	2P/HSI0
-	-	-	-	GND (Bank 0)	-	-
C1	BK0_IO7	HSI0A_SINN	3N/HSI0	BK0_IO5	HSI0A_SINN	2N/HSI0
D3	BK0_IO8	-	4P/HSI0	BK0_IO6	-	3P/HSI0
E3	BK0_IO9	VREF0	4N/HSI0	BK0_IO7	VREF0	3N/HSI0
D1	BK0_IO10	HSI0B_SOUTP	5P/HSI0	BK0_IO8	HSI0B_SOUTP	4P/HSI0
-	GND (Bank 0)	-	-	-	-	-
E1	BK0_IO11	HSI0B_SOUTN	5N/HSI0	BK0_IO9	HSI0B_SOUTN	4N/HSI0
E2	BK0_IO12	-	6P/HSI0	BK0_IO10	-	5P/HSI0
F2	BK0_IO13	-	6N/HSI0	BK0_IO11	-	5N/HSI0
F1	BK0_IO14	HSI0B_SINP	7P/HSI0	BK0_IO12	HSI0B_SINP	6P/HSI0
-	-	-	-	GND (Bank 0)	-	-
G1	BK0_IO15	HSI0B_SINN	7N/HSI0	BK0_IO13	HSI0B_SINN	6N/HSI0
F3	BK0_IO18	PLL_FBK0	9P	BK0_IO14	PLL_FBK0	7P/HSI0
-	GND (Bank 0)	-	-	-	-	-
G2	BK0_IO19	PLL_RST1	9N	BK0_IO15	PLL_RST1	7N/HSI0
E4	BK0_IO20	-	10P	BK0_IO16	-	8P/HSI0
F4	BK0_IO21	PLL_FBK1	10N	BK0_IO17	PLL_FBK1	8N/HSI0
H1	BK0_IO22	PLL_RST0	11P	BK0_IO18	PLL_RST0	9P
-	-	-	-	GND (Bank 0)	-	-
J1	BK0_IO23	-	11N	BK0_IO19	-	9N
H2	BK0_IO24	CLK_OUT0	12P	BK0_IO20	CLK_OUT0	10P
G3	BK0_IO25	CLK_OUT1	12N	BK0_IO21	CLK_OUT1	10N
-	GND (Bank 0)	-	-	-	-	-
G4	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P
H4	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N
H3	VCCP0	-	-	VCCP0	-	-
J4	GNDP0	-	-	GNDP0	-	-
J2	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P
J3	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N
-	GND (Bank 1)	-	-	-	-	-
H5	BK1_IO0	CLK_OUT2	13P	BK1_IO0	CLK_OUT2	11P
J5	BK1_IO1	CLK_OUT3	13N	BK1_IO1	CLK_OUT3	11N
K1	BK1_IO2	SS_CLKOUT0P	14P	BK1_IO2	SS_CLKOUT0P	12P
-	-	-	-	GND (Bank 1)	-	-
L1	BK1_IO3	SS_CLKOUT0N	14N	BK1_IO3	SS_CLKOUT0N	12N
K4	BK1_IO4	PLL_FBK2	15P	BK1_IO4	PLL_FBK2	13P
L4	BK1_IO5	PLL_FBK3	15N	BK1_IO5	PLL_FBK3	13N
K3	BK1_IO6	SS_CLKIN0P	16P	BK1_IO6	SS_CLKIN0P	14P

ispXPGA Logic Signal Connections: 256-Ball fpBGA (Cont.)

256-fpBGA Ball	LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ²	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ²
C8	BK7_IO1	-	91N	BK7_IO1	-	77N
B8	BK7_IO2	-	92P	BK7_IO2	-	78P
B7	BK7_IO3	-	92N	BK7_IO3	-	78N
A9	BK7_IO6	-	94P	BK7_IO4	-	79P
-	GND (Bank 7)	-	-	-	-	-
A8	BK7_IO7	-	94N	BK7_IO5	-	79N
C7	BK7_IO10	-	96P	BK7_IO6	-	80P
D7	BK7_IO11	-	96N	BK7_IO7	-	80N
D6	BK7_IO12	-	97P	BK7_IO8	-	81P
-	-	-	-	GND (Bank 7)	-	-
C6	BK7_IO13	-	97N	BK7_IO9	-	81N
B6	BK7_IO14	-	98P	BK7_IO10	-	82P
-	GND (Bank 7)	-	-	-	-	-
B5	BK7_IO15	-	98N	BK7_IO11	-	82N
A7	BK7_IO16	VREF7	99P	BK7_IO12	VREF7	83P
A6	BK7_IO17	-	99N	BK7_IO13	-	83N
D5	BK7_IO18	-	100P	BK7_IO14	-	84P
C5	BK7_IO19	-	100N	BK7_IO15	-	84N
A5	BK7_IO20	-	101P	BK7_IO16	-	85P
-	-	-	-	GND (Bank 7)	-	-
A4	BK7_IO21	-	101N	BK7_IO17	-	85N
B4	BK7_IO22	-	102P	BK7_IO18	-	86P
-	GND (Bank 7)	-	-	-	-	-
B3	BK7_IO23	-	102N	BK7_IO19	-	86N
A3	TDO	-	-	TDO	-	-
A2	VCCJ	-	-	VCCJ	-	-
C4	TDI	-	-	TDI	-	-

1. Not available for differential pairs.

2. If a sysHSI Block is used, the indicated sysHSI reserved pins are unavailable for general purpose I/O use.

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

516-Ball BGA Ball	LFX500			LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ¹	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ¹	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ¹
D21	BK6_IO20	-	136P	BK6_IO8	-	82P	BK6_IO8	-	70P
C21	BK6_IO21	VREF6	136N	BK6_IO9	VREF6	82N	BK6_IO9	VREF6	70N
B21	BK6_IO22	DATA5	137P	BK6_IO10	DATA5	83P	BK6_IO10	DATA5	71P
-	-	-	-	GND (Bank 6)	-	-	-	-	-
A21	BK6_IO23	DATA4	137N	BK6_IO11	DATA4	83N	BK6_IO11	DATA4	71N
D20	BK6_IO24	-	138P	BK6_IO12	-	84P	BK6_IO12	-	72P
-	-	-	-	-	-	-	GND (Bank 6)	-	-
C20	BK6_IO25	-	138N	BK6_IO13	-	84N	BK6_IO13	-	72N
B20	BK6_IO26	DATA3	139P	BK6_IO14	DATA3	85P	BK6_IO14	DATA3	73P
-	GND (Bank 6)	-	-	-	-	-	-	-	-
A20	BK6_IO27	DATA2	139N	BK6_IO15	DATA2	85N	BK6_IO15	DATA2	73N
C19	BK6_IO28	-	140P	BK6_IO16	-	86P	BK6_IO16	-	74P
B19	BK6_IO29	-	140N	BK6_IO17	-	86N	BK6_IO17	-	74N
A19	BK6_IO30	DATA1	141P	BK6_IO18	DATA1	87P	BK6_IO18	DATA1	75P
-	-	-	-	GND (Bank 6)	-	-	GND (Bank 6)	-	-
A18	BK6_IO31	DATA0	141N	BK6_IO19	DATA0	87N	BK6_IO19	DATA0	75N
D18	BK6_IO32	-	142P	BK6_IO20	-	88P	BK6_IO20	-	76P
C18	BK6_IO33	-	142N	BK6_IO21	-	88N	BK6_IO21	-	76N
B18	BK6_IO34	-	143P	BK6_IO22	-	89P	NC	-	-
-	GND (Bank 6)	-	-	-	-	-	-	-	-
C17	BK6_IO35	-	143N	BK6_IO23	-	89N	NC	-	-
B17	BK6_IO36	-	144P	NC	-	-	NC	-	-
A17	BK6_IO37	-	144N	NC	-	-	NC	-	-
D16	BK6_IO38	-	145P	NC	-	-	NC	-	-
C16	BK6_IO39	-	145N	NC	-	-	NC	-	-
B16	BK6_IO40	-	146P	BK6_IO24	-	90P	NC	-	-
A16	BK6_IO41	-	146N	BK6_IO25	-	90N	NC	-	-
-	GND (Bank 6)	-	-	GND (Bank 6)	-	-	-	-	-
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-	-	-	-
A15	BK7_IO0	-	147P	BK7_IO0	-	91P	BK7_IO0	-	77P
B15	BK7_IO1	-	147N	BK7_IO1	-	91N	BK7_IO1	-	77N
C15	BK7_IO2	-	148P	BK7_IO2	-	92P	BK7_IO2	-	78P
-	-	-	-	-	-	-	GND (Bank 7)	-	-
D15	BK7_IO3	-	148N	BK7_IO3	-	92N	BK7_IO3	-	78N
A14	BK7_IO4	-	149P	BK7_IO4	-	93P	BK7_IO4	-	79P
B14	BK7_IO5	-	149N	BK7_IO5	-	93N	BK7_IO5	-	79N
C14	BK7_IO6	-	150P	BK7_IO6	-	94P	NC	-	-
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-	-	-	-
A13	BK7_IO7	-	150N	BK7_IO7	-	94N	NC	-	-
B13	BK7_IO8	-	151P	BK7_IO8	-	95P	NC	-	-
C13	BK7_IO9	-	151N	BK7_IO9	-	95N	NC	-	-
D13	BK7_IO10	-	152P	BK7_IO10	-	96P	BK7_IO6	-	80P
B12	BK7_IO11	-	152N	BK7_IO11	-	96N	BK7_IO7	-	80N
C12	BK7_IO12	-	153P	BK7_IO12	-	97P	BK7_IO8	-	81P
-	-	-	-	-	-	-	GND (Bank 7)	-	-
A12	BK7_IO13	-	153N	BK7_IO13	-	97N	BK7_IO9	-	81N
A11	BK7_IO14	-	154P	BK7_IO14	-	98P	BK7_IO10	-	82P
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-	-	-	-
B11	BK7_IO15	-	154N	BK7_IO15	-	98N	BK7_IO11	-	82N
C11	BK7_IO16	-	155P	NC	-	-	NC	-	-
D11	BK7_IO17	-	155N	NC	-	-	NC	-	-

ispXPGA Logic Signal Connections: 680-Ball fpBGA (Cont.)

LFX1200			
680-Ball fpBGA	Signal Name	Second Function	LVDS Pair/sysHSI Reserved ¹
L3	BK7_IO35	-	234N
J1	BK7_IO36	-	235P
J2	BK7_IO37	-	235N
M4	BK7_IO38	-	236P
H1	BK7_IO39	-	236N
J3	BK7_IO40	-	237P
L4	BK7_IO41	-	237N
M5	BK7_IO42	-	238P
-	GND (Bank 7)	-	-
H2	BK7_IO43	-	238N
K4	BK7_IO44	-	239P
G1	BK7_IO45	-	239N
H3	BK7_IO46	-	240P
J4	BK7_IO47	VREF7	240N
K5	BK7_IO48	-	241P
G3	BK7_IO49	-	241N
H4	BK7_IO50	-	242P
-	GND (Bank 7)	-	-
F2	BK7_IO51	-	242N
G2	BK7_IO52	-	243P
H5	BK7_IO53	-	243N
F3	BK7_IO54	-	244P
F1	BK7_IO55	-	244N
G4	BK7_IO56	-	245P
E1	BK7_IO57	-	245N
F4	BK7_IO58	-	246P
-	GND (Bank 7)	-	-
E2	BK7_IO59	-	246N
F5	BK7_IO60	-	247P
E3	BK7_IO61	-	247N
D2	TDO	-	-
D3	VCCJ	-	-
D1	TDI	-	-

1. If a sysHSI Block is used, the indicated sysHSI reserved pins are unavailable for general purpose I/O use.

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ¹	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved ¹
K30	BK5_IO22	HSI7B_SOUTP	166P/HSI8	BK5_IO22	HSI4B_SOUTP	116P/HSI4
-	-	-	-	GND (Bank 5)	-	-
K29	BK5_IO23	HSI7B_SOUTN	166N/HSI8	BK5_IO23	HSI4B_SOUTN	116N/HSI4
L28	BK5_IO24	-	167P/HSI8	BK5_IO24	-	117P/HSI5
L27	BK5_IO25	-	167N/HSI8	BK5_IO25	-	117N/HSI5
L26	BK5_IO26	HSI8A_SINP	168P/HSI8	BK5_IO26	HSI5A_SINP	118P/HSI5
-	GND (Bank 5)	-	-	-	-	-
L25	BK5_IO27	HSI8A_SINN	168N/HSI8	BK5_IO27	HSI5A_SINN	118N/HSI5
K27	BK5_IO28	-	169P/HSI8	BK5_IO28	-	119P/HSI5
K26	BK5_IO29	-	169N/HSI8	BK5_IO29	-	119N/HSI5
J30	BK5_IO30	HSI8A_SOUTP	170P/HSI8	BK5_IO30	HSI5A_SOUTP	120P/HSI5
-	-	-	-	GND (Bank 5)	-	-
J29	BK5_IO31	HSI8A_SOUTN	170N/HSI8	BK5_IO31	HSI5A_SOUTN	120N/HSI5
J26	BK5_IO32	-	171P/HSI8	NC	-	-
J27	BK5_IO33	-	171N/HSI8	NC	-	-
H30	BK5_IO34	HSI8B_SINP	172P/HSI8	NC	-	-
-	GND (Bank 5)	-	-	-	-	-
H29	BK5_IO35	HSI8B_SINN	172N/HSI8	NC	-	-
J25	BK5_IO36	-	173P/HSI9	NC	-	-
J24	BK5_IO37	-	173N/HSI9	NC	-	-
G30	BK5_IO38	HSI8B_SOUTP	174P/HSI9	NC	-	-
G29	BK5_IO39	HSI8B_SOUTN	174N/HSI9	NC	-	-
H27	BK5_IO40	-	175P/HSI9	NC	-	-
H28	BK5_IO41	-	175N/HSI9	NC	-	-
F30	BK5_IO42	HSI9A_SINP	176P/HSI9	NC	-	-
-	GND (Bank 5)	-	-	-	-	-
F29	BK5_IO43	HSI9A_SINN	176N/HSI9	NC	-	-
G27	BK5_IO44	-	177P/HSI9	NC	-	-
G28	BK5_IO45	-	177N/HSI9	NC	-	-
E30	BK5_IO46	HSI9A_SOUTP	178P/HSI9	NC	-	-
E29	BK5_IO47	HSI9A_SOUTN	178N/HSI9	NC	-	-
H26	BK5_IO48	-	179P/HSI9	BK5_IO33	-	121N/HSI5
H25	BK5_IO49	VREF5	179N/HSI9	BK5_IO32	VREF5	121P/HSI5
D30	BK5_IO50	HSI9B_SINP	180P/HSI9	BK5_IO34	HSI5B_SINP	122P/HSI5
-	GND (Bank 5)	-	-	-	-	-
D29	BK5_IO51	HSI9B_SINN	180N/HSI9	BK5_IO35	HSI5B_SINN	122N/HSI5
F28	BK5_IO52	-	181P	BK5_IO36	-	123P/HSI5
F27	BK5_IO53	-	181N	BK5_IO37	-	123N/HSI5
C30	BK5_IO54	HSI9B_SOUTP	182P	BK5_IO38	HSI5B_SOUTP	124P/HSI5
-	-	-	-	GND (Bank 5)	-	-
C29	BK5_IO55	HSI9B_SOUTN	182N	BK5_IO39	HSI5B_SOUTN	124N/HSI5
G26	BK5_IO56	-	183P	NC	-	-

“E-Series” Commercial (Cont.)

Part Number	Gates	Voltage	Speed Grade	Package	Balls
LFX500EC-04FN900C	476K	1.8	-4	Lead-Free fpBGA	900
LFX500EC-03FN900C	476K	1.8	-3	Lead-Free fpBGA	900

“E-Series” Industrial

Part Number	Gates	Voltage	Speed Grade	Package	Balls
LFX125EB-04FN256I	139K	2.5/3.3	-4	Lead-Free fpBGA	256
LFX125EB-03FN256I	139K	2.5/3.3	-3	Lead-Free fpBGA	256
LFX125EC-03FN256I	139K	1.8	-3	Lead-Free fpBGA	256
LFX200EB-04FN256I	210K	2.5/3.3	-4	Lead-Free fpBGA	256
LFX200EB-03FN256I	210K	2.5/3.3	-3	Lead-Free fpBGA	256
LFX200EC-03FN256I	210K	1.8	-3	Lead-Free fpBGA	256
LFX500EB-04FN900I	476K	2.5/3.3	-4	Lead-Free fpBGA	900
LFX500EB-03FN900I	476K	2.5/3.3	-3	Lead-Free fpBGA	900
LFX500EC-03FN900I	476K	1.8	-3	Lead-Free fpBGA	900

For Further Information

In addition to this data sheet, the following Lattice technical notes may be helpful when designing with the ispXPGA Family:

- TN1028, [ispXPGA Memory Usage Guidelines](#)
- TN1003, [sysCLOCK PLL Usage and Design Guidelines](#)
- TN1000, [sysIO Usage Guidelines for Lattice Devices](#)
- TN1026, [ispXP Configuration Usage Guidelines](#)
- TN1020, [sysHSI Usage Guidelines](#)
- TN1043, [Power Estimation in ispXPGA Devices](#)

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
September 2003	07	Improved typical Icc data for LFX125B/C and LFX500B/C.
		Improved external switching characteristics timing numbers for LFX125B/C.
		Improved PIC timing numbers for LFX125B/C.
		Improved t _{IOINDLY} timing numbers for LFX125B/C.
		Improved external switching characteristics timing numbers for LFX500B/C.
		Improved PIC timing numbers for LFX500B/C.
		Improved t _{IOINDLY} timing numbers for LFX500B/C.
		Enhanced CDR functionality description.
January 2004	07.1	Logic Signal Connections and Signal Descriptions - removed CDRLOCK, LOSS and EXLOSS descriptions.
		Added lead-free package designators.
June 2004	08.0	Updated CDR specifications and reference notes. Removed Source Synchronous (SS:No CAL) mode references for the sysHSI blocks.
		Revised Figures 16 and 24 for clarification.
		Clarification of VCC sysHSI Block for 1.8V devices.
		Updated IIL and IIH max specification.
		Updated LVTTTL and PCI 3.3 to support 5V tolerance.

Revision History (Cont.)

Date	Version	Change Summary
June 2004 (cont.)	08.0 (cont.)	Updated Global Clock Input Setup time specifications.
		Clarification of Serial Out LVDS test condition.
		Clarification of REFCLK, SS_CLKIN peak-to-peak period jitter condition.
		Added sysHSI Reserved pins and footnote.
		Removed industrial ordering part numbers.
July 2004	09.0	Added "E" Series product family.
August 2004	10.0	Final release.
December 2004	10.1	Updated NC Connections table.
April 2005	10.2	Clarification of IDK specification.
April 2005	11.0	Select lead-free packages release.
July 2005	12.0	Added lead-free 516 fpBGA ordering part numbers.
April 2007	13.0	Removed lead-free 680 fpSBGA information from Part Number Description and Ordering Part Number tables. Removed lead-free 516 fpBGA for LFX125 from Ordering Part Number tables.
November 2007	14.0	Removed lead-free 516 fpBGA information from Part Number Description and Ordering Part Number tables.
July 2008	14.1	Added 516 fpBGA package without heat spreader to Part Number Description and Ordering Part Number tables.
February 2010	15.0	Ordering part numbers and ispXPGA Family Selection Guide table have been updated per PCN #03A-10 (discontinuation of the ispXPGA 1200 devices).
		References to "system gates" changed to "functional gates."